

IN THE CLAIMS:

Please cancel Claim 29 without prejudice or disclaimer of the subject matter recited therein.

Please amend Claim 28 and add new Claim 32 as follows.

Claims 1-27. (Cancelled).

28. (Currently Amended) A method of manufacturing an image display apparatus having display devices and an airtight container containing the display devices, comprising a step of bonding a substrate to and a frame ~~for forming an airtight space together with the substrate through~~ forming the airtight container using a seal bonding material containing a low melting point metal, wherein the step of bonding includes:

a step of contacting the substrate with the frame to form a contacting region between the substrate and the frame ~~providing a seal bonding material along a corner between the frame and the substrate formed by setting the frame and the substrate to abut on each other; and~~

a step of placing the seal bonding material, along the contacting region, on a surface of the substrate or the frame except for opposing surfaces of the substrate and the frame, under a state of contacting the substrate with the frame; and

a step of heating successively the seal bonding material placed along the contacting region, such that the seal bonding material is melted, and a part of the seal bonding

~~material melted is introduced between opposing surfaces of the substrate and the frame to a temperature equal to or higher than a temperature at which the seal bonding material can perform bonding of the substrate to the frame, successively along the corner,~~

wherein the seal bonding material melted by the heating is introduced ~~between opposing surfaces of the frame and the substrate~~ between the substrate and the frame is performed by the seal bonding material introduced between the opposing surfaces of the substrate and the frame, and by the seal bonding material placed on the surface of the substrate or the frame except for the opposing surfaces of the substrate and the frame.

Claim 29. (Cancelled).

30. (Previously Presented) The method according to claim 28, wherein the step of heating is performed within a vacuum atmosphere.

31. (Previously Presented) The method according to claim 28, further comprising a step of forming on a portion, on which the seal bonding material is to be provided, a material of good wettability to the seal bonding material as an underlying film.

32. (New) The method according to claim 28, wherein the step of placing the seal bonding material is a step of placing the seal bonding material on the surfaces of the substrate and the frame except for the opposing surfaces of the substrate and the frame, and the

seal bonding between the substrate and the frame is performed by the seal bonding material introduced between the opposing surfaces of the substrate and the frame, and by the seal bonding material placed on the surfaces of the substrate and the frame except for the opposing surfaces of the substrate and the frame.